

AW-CU544

IEEE 802.11 b/g/n MAC/baseband/radio and Bluetooth 5.2 IoT Module

Layout Guide

Rev. A

(For Standard)



Revision History

Version	Revision Date	Description	Initials	Approved
Α	2022/11/06	Initial Version	Steven Jian	Chihhao Liao



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1. Layout guide

1.1 Power & Digital Signal

- Pin E1 and F1 are the main power line for CYW43438. Keep its impedance as low as possible.
 Recommended trace width>20mils. DO NOT use Coin Cells for this rail. They are designed for low power device (<10mA), whereas the CYW43438 can consume up to 300mA average current.
- Make sure every power traces have good return path (ground path).
- High speed digital traces shall have equal electrical length within their respective group.
 Keep them away from noise sensitive blocks (e.g. antenna, CapSense and power traces).
- Good return path and well shielded signal can reduce crosstalk, EMI emission and improve signal integrity.
- Traces for CapSense function should be short and narrow (recommend use Port 8 for its low self-capacitance traces inside the module).
- Use mutual-capacitance sensing method so that the sensitivity is not degraded because of high self-capacitance of the trace (refer to AN85951 - PSoC® 4 and PSoC® 6 MCU CapSense® Design Guide)

1.2 Antenna

- P + Q > 20mm
- R = 7.65mm
- Keep out distance(XYZ direction) "S" of the print antenna is > 10mm for non-conductive materials
 (e.g. plastic case) & 20mm for conductive materials (e.g. cables & connectors)
- Do not extend main board PCB outline to the antenna area.
- Above is the general guideline. Contact us if it does not fit your design.



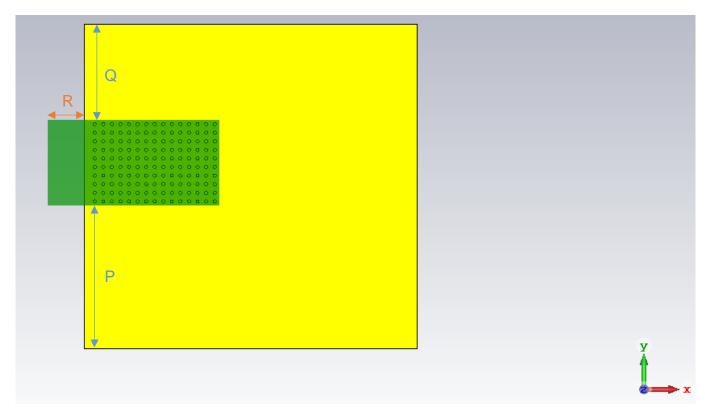


Figure 1

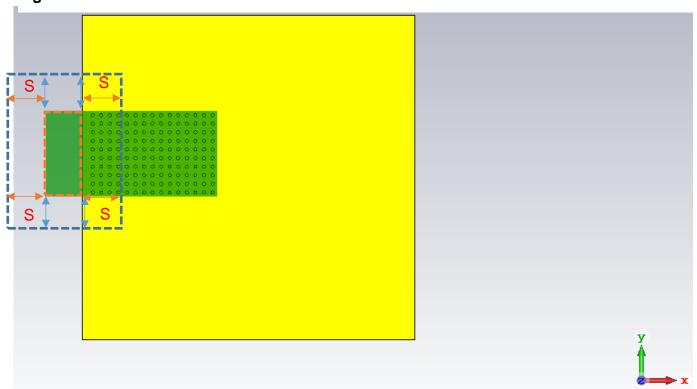


Figure 2



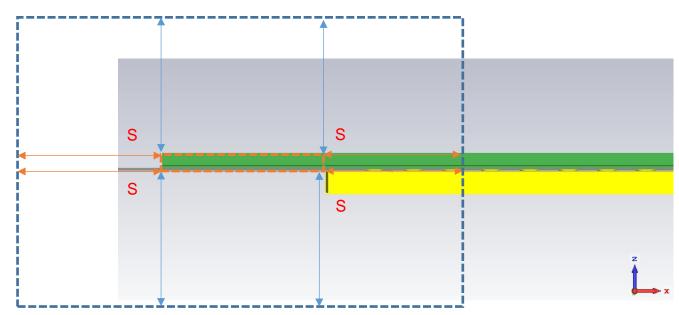
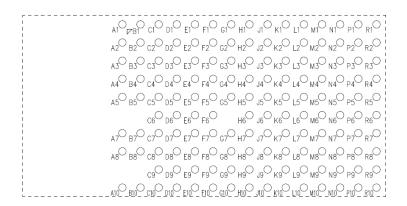
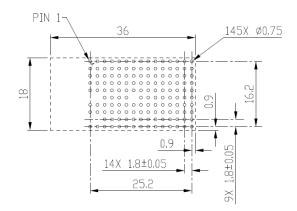


Figure 3



1.3 Recommended PCB Footprint





PIN DEFINED (TOP VIEW)

Figure 4

Recommended PCB Layout Footprint (Unit in mm Dia=0.75mm Solder Mask Defined)